



#### 30V N-CHANNEL ENHANCEMENT MODE MOSFET H-BRIDGE

## **Product Summary**

BV <sub>DSS</sub>	R <sub>DS(ON)</sub> Max	I <sub>D</sub> Max T <sub>A</sub> = +25°C		
30V	$10m\Omega @ V_{GS} = 10V$	13A		
30 V	$15m\Omega @ V_{GS} = 4.5V$	11A		

#### **Features**

- Low On-Resistance
- Low Input Capacitance
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)

### **Description**

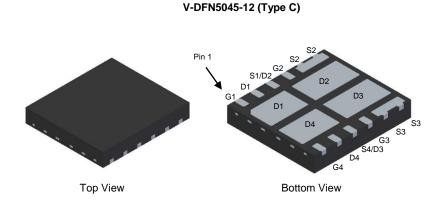
This MOSFET is designed to minimize the on-state resistance (R<sub>DS(ON)</sub>), yet maintain superior switching performance, making it ideal for high efficiency power management applications.

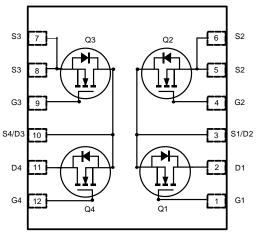
## **Applications**

· High-Efficiency Bridge Rectifiers

#### **Mechanical Data**

- Case: V-DFN5045-12
- Case Material: Molded Plastic, "Green" Molding Compound.
   UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish NiPdAu over Copper Leadframe.
   Solderable per MIL-STD-202, Method 208 @4
- Weight: 0.056grams (Approximate)





Internal Schematic Top View

## **Ordering Information** (Note 4)

Part Number	Case	Quantity per Reel
DMHT3006LFJ-13	V-DFN5045-12 (Type C)	3000

Notes:

- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant.
- 2. See https://www.diodes.com/quality/lead-free/ for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at https://www.diodes.com/design/support/packaging/diodes-packaging/.

# **Marking Information**



⊃¦¦ = Manufacturer's Marking T306LJ = Product Type Marking Code YYWW = Date Code Marking YY = Year (ex: 18 = 2018) WW = Week (01 to 53)



# 

Characteristic	Symbol	Value	Unit		
Drain-Source Voltage			$V_{DSS}$	30	V
Gate-Source Voltage			$V_{GSS}$	±20	V
Continuous Drain Current (Note 6) V <sub>GS</sub> = 10V Steady State		$T_A = +25^{\circ}C$ $T_A = +70^{\circ}C$	I <sub>D</sub>	13 10	А
Pulsed Drain Current (10µs Pulse, Duty Cycle = 1%)			I <sub>DM</sub>	80	Α
Continuous Source-Drain Diode Current (Note 6) T <sub>A</sub> =			Is	2	А
Avalanche Current (Note 7) L = 0.1mH			I <sub>AS</sub>	23	Α
Avalanche Energy (Note 7) L = 0.1mH			Eas	28	mJ

## **Thermal Characteristics**

Characteristic	Symbol	Value	Unit	
Total Power Dissipation (Note 5)	$T_A = +25$ °C	P <sub>D</sub>	1.3	W
Thermal Resistance, Junction to Ambient (Note 5)  Steady State		$R_{\theta JA}$	95	°C/W
Total Power Dissipation (Note 6)		P <sub>D</sub>	2.1	W
Thermal Resistance, Junction to Ambient (Note 6)  Steady State		$R_{\theta JA}$	60	°C/W
Thermal Resistance, Junction to Case (Note 6)		R <sub>0</sub> JC	22	°C/W
Operating and Storage Temperature Range	$T_{J_i}T_{STG}$	-55 to +150	°C	

# **Electrical Characteristics** (@T<sub>A</sub> = +25°C, unless otherwise specified.)

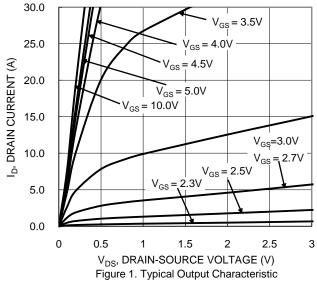
Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition	
OFF CHARACTERISTICS (Note 8)	-	•		•	•	•	
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	30	-	_	V	$V_{GS} = 0V, I_D = 250\mu A$	
Zero Gate Voltage Drain Current (T <sub>J</sub> = +25°C)	I <sub>DSS</sub>	_	_	1	μΑ	$V_{DS} = 24V, V_{GS} = 0V$	
Gate-Source Leakage	I <sub>GSS</sub>	_	_	±100	nA	$V_{GS} = +20V, V_{DS} = 0V$ $V_{GS} = -16V, V_{DS} = 0V$	
ON CHARACTERISTICS (Note 8)		•		•	•		
Gate Threshold Voltage	V <sub>GS(TH)</sub>	1.0	_	3.0	V	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	
Static Drain-Source On-Resistance	В		5.8	10	0	$V_{GS} = 10V, I_D = 10A$	
Static Drain-Source On-Resistance	R <sub>DS(ON)</sub>	_	7.8	15	mΩ	$V_{GS} = 4.5V, I_D = 8A$	
Diode Forward Voltage	V <sub>SD</sub>	_	0.7	1.0	V	$V_{GS} = 0V, I_{S} = 2A$	
DYNAMIC CHARACTERISTICS (Note 9)						•	
Input Capacitance	C <sub>iss</sub>	_	1171	_		$V_{DS} = 15V, V_{GS} = 0V,$ f = 1.0MHz	
Output Capacitance	Coss	_	421	_	pF		
Reverse Transfer Capacitance	C <sub>rss</sub>	_	63	_			
Gate Resistance	Rq	_	1.9	_	Ω	$V_{DS} = 0V, V_{GS} = 0V, f = 1.0MHz$	
Total Gate Charge (V <sub>GS</sub> = 4.5V)	Qg	_	9.0	_			
Total Gate Charge (V <sub>GS</sub> = 10V)	Qq	_	17	_		$V_{DD} = 15V, I_D = 9A$	
Gate-Source Charge	Q <sub>qs</sub>	_	2.7	_	nC		
Gate-Drain Charge	Q <sub>qd</sub>	_	4.7	_			
Turn-On Delay Time	t <sub>D(ON)</sub>	_	7.4	_		$V_{DD} = 15V, V_{GS} = 10V,$ $R_q = 3\Omega, I_D = 9A$	
Turn-On Rise Time	t <sub>R</sub>	_	54	_			
Turn-Off Delay Time	t <sub>D(OFF)</sub>	_	16	_	ns		
Turn-Off Fall Time	t <sub>F</sub>	_	4.3	_			
Reverse Recovery Time	t <sub>RR</sub>	_	18	_	ns	1 154 11/14 1004/	
Reverse Recovery Charge	Q <sub>RR</sub>	_	8.5	_	$_{\rm nC}$ I <sub>F</sub> = 1.5A, di/dt = 100A/µs		

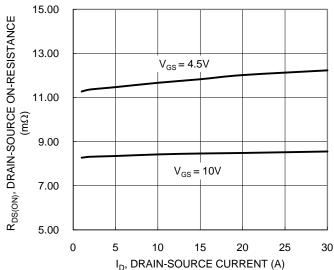
Device mounted on FR-4 substrate PC board, 2oz copper, with minimum recommended pad layout.
 Device mounted on FR-4 substrate PC board, 2oz copper, with 1inch square copper plate.

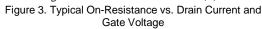
<sup>7.</sup>  $I_{AS}$  and  $E_{AS}$  ratings are based on low frequency and duty cycles to keep  $T_{J}$  = +25°C.

Short duration pulse test used to minimize self-heating effect.
 Guaranteed by design. Not subject to product testing.









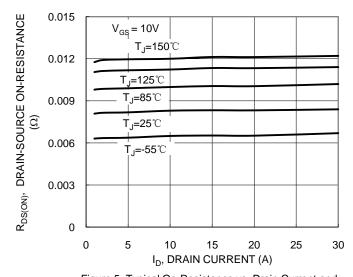


Figure 5. Typical On-Resistance vs. Drain Current and Temperature

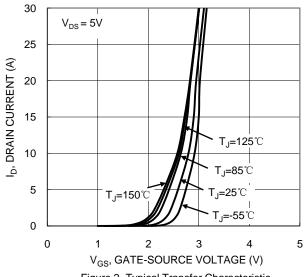


Figure 2. Typical Transfer Characteristic

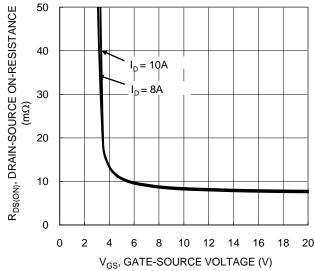


Figure 4. Typical Transfer Characteristic

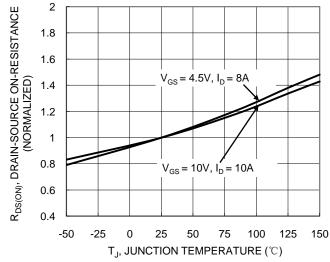


Figure 6. On-Resistance Variation with Temperature





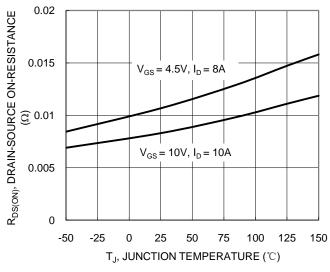
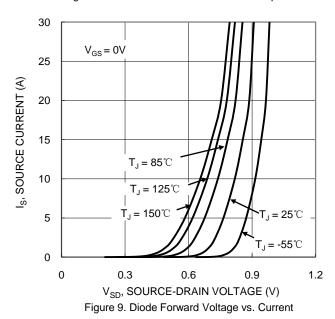


Figure 7. On-Resistance Variation with Temperature



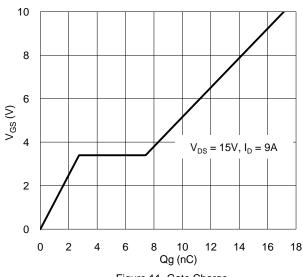


Figure 11. Gate Charge

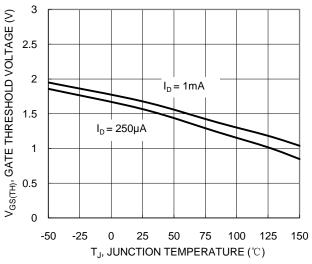
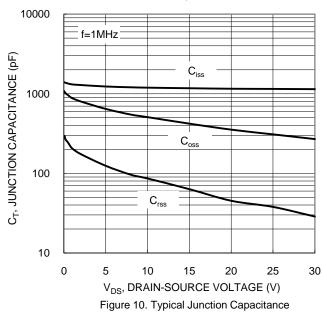
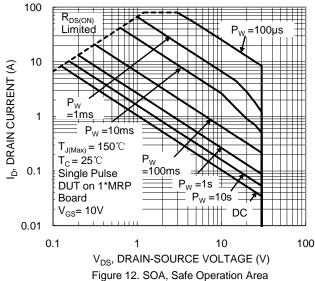


Figure 8. Gate Threshold Variation vs. Junction Temperature







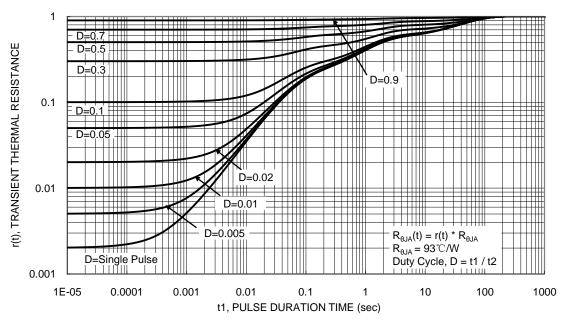


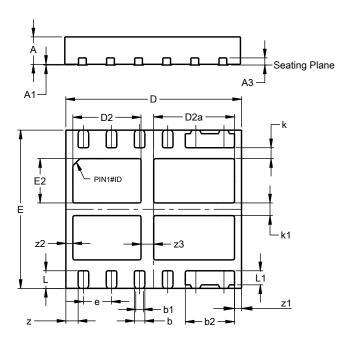
Figure 13. Transient Thermal Resistance



# **Package Outline Dimensions**

Please see http://www.diodes.com/package-outlines.html for the latest version.

### V-DFN5045-12 (Type C)

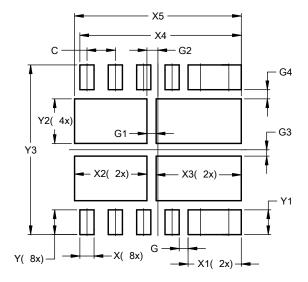


V-DFN5045-12 (Type C)					
Dim			Тур		
Α	0.75	0.85	0.80		
A1	0.00	0.05	0.02		
A3			0.203		
b	0.25	0.35	0.30		
b1	0.17	0.27	0.22		
b2	1.35	1.45	1.40		
D	4.95	5.05	5.00		
D2	1.84	2.04	1.94		
D2a	2.20	2.40	2.30		
е			0.80		
Е	4.45	4.55	4.50		
E2	1.16	1.36	1.26		
k			0.31		
k1			0.36		
L	0.45	0.55	0.50		
L1	0.35	0.45	0.40		
Z			0.35		
z1			0.20		
z2			0.20		
z3			0.36		
All Dimensions in mm					

# **Suggested Pad Layout**

Please see http://www.diodes.com/package-outlines.html for the latest version.

#### V-DFN5045-12 (Type C)



Dimensions	Value			
פוווופוופוווט	(in mm)			
С	0.800			
G	0.250			
G1	0.260			
G2	0.310			
G3	0.180			
G4	0.260			
Х	0.400			
X1	1.500			
X2	2.040			
Х3	2.400			
X4	4.550			
X5	4.700			
Υ	0.700			
Y1	0.700			
Y2	1.260			
Y3	4.800			
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